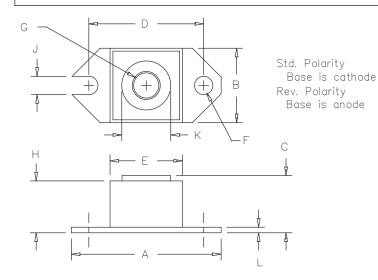
240 Amp Schottky Rectifier HS246150



Dim	. Inches		Millimeter	-	
	Minimum	Maximum	Minimum	Maximum	Notes
A B C D E	1.52 .725 .605 1.182 .745	1.56 .775 .625 1.192 .755	38.61 18.42 15.37 30.02 18.92 3.86	39.62 19.69 15.88 30.28 19.18 4.06	Sq. Dia.
r G H J K L	.525 .156 .495 .120	.160 1/4-20 .580 .160 .505 .130		14.73 4.06 12.83 3.30	Dia.

Microsemi Industry Working Peak Repetitive Peak Catalog Number Part Number Reverse Voltage Reverse Voltage HS246150* 249NQ150 150V 150V

*Add Suffix R for Reverse Polarity

- Schottky Barrier Rectifier
- Guard Ring Protection
- 240 Amperes 150 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

Average forward current
Maximum surge current
Maximum repetitive reverse current
Typical peak forward voltage
Max peak forward voltage
Typical peak reverse current
Max peak reverse current
Typical junction capacitance

|F(AV) 240 Amps |FSM 3300 Amps |R(OV) 2 Amps |VFM 0.65 Volts |VFM 0.86 Volts |RM 150mA |RM 8.0mA ^{T}C = 118°C, Square wave, $^{R}\Theta JC$ = .24°C/W 8.3ms, half sine, ^{T}J = 175°C f = 1 KHZ, 25°C I FM = 240A: ^{T}J = 175°C*

IFM = 240A: TJ = 25°C*
VRRM, TJ = 125°C*
VRRM, TJ = 25°C
VR = 5.0V, TC = 25°C

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

6000pF

Thermal and Mechanical Characteristics

Storage temp range
Operating junction temp range
Max thermal resistance
Typical thermal resistance (greased)
Terminal Torque
Mounting Base Torque
Weight

TSTG TJ R OJC R OCS

 C_{\cup}

-55°C to 175°C -55°C to 175°C 0.21°C/W Junction to case 0.12°C/W Case to sink 35-40 inch pounds 20-25 inch pounds

1.1 ounces (32 grams) typical



HS246150

Figure 1 Typical Forward Characteristics

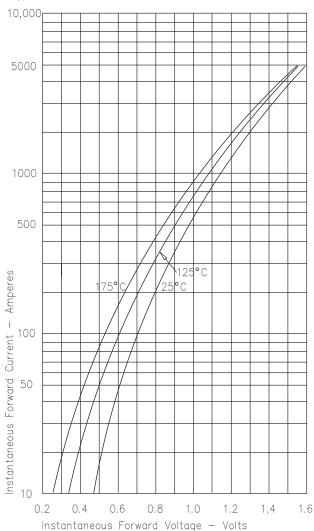


Figure 3 Typical Junction Capacitance

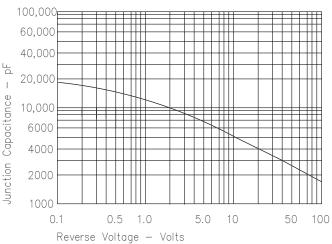


Figure 4

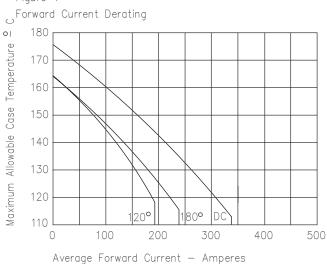


Figure 2 Typical Reverse Characteristics

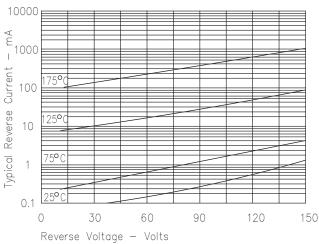
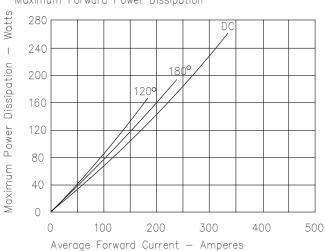


Figure 5 Maximum Forward Power Dissipation





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